



DESCRIPTION

The SM4001~SM4007 are available in DO-213AB Package

FEATURES

- Glass passivated device
- Ideal for surface mounted applications
- Low leakage current
- Metallurgically bonded construction
- Available in DO-213AB Package

ORDERING INFORMATION

Package Type	Part Number
DO-213AB	SM4001
	SM4002
	SM4003
	SM4004
	SM4005
	SM4006
	SM4007
Note	SPQ: 5,000pcs/Reel
AiT provides all RoHS Compliant Products	

MECHANICAL DATA

Case: JEDEC DO-213AB, molded plastic over passivated chip

Terminals: Solder Plated, solderable per MIL-STD-750, Method 2026

Polarity: Color band denotes cathode end

Weight: 0.0046 ounces, 0.116gram

Mounting position: Any



ABSOLUTE MAXIMUM RATINGS AND ELECTRICAL CHARACTERISTICS

Ratings at 25°C ambient temperature unless otherwise specified. Single phase, half wave, 60Hz, resistive or inductive load. For capacitive load, derate by 20 %

Parameter		Symbol	SM4001	SM4002	SM4003	SM4004	SM4005	SM4006	SM4007	Unit
Maximum Recurrent Peak Reverse Voltage		V_{RRM}	50	100	200	400	600	800	1000	V
Maximum RMS Voltage		V_{RMS}	35	70	140	280	420	560	700	V
Maximum DC Blocking Voltage		V_{DC}	50	100	500	400	600	800	1000	V
Maximum Average Forward Rectified Current $T_A=75^{\circ}\text{C}$		$I_{F(AV)}$	1.0							A
Peak Forward Surge Current 8.3ms Single Half Sine Wave Superimposed on Rated Load (JEDEC Method)		I_{FSM}	30							A
Maximum Forward Voltage at 1A		V_F	1.1							V
Maximum DC Reverse Current at Rated DC Blocking Voltage	$T_A=25^{\circ}\text{C}$ $T_A=125^{\circ}\text{C}$	I_R	5.0 50							μA
Typical Junction Capacitance ^{NOTE1}		C_J	15							pF
Typical Thermal Resistance ^{NOTE2}		$R_{\theta JL}$	20							$^{\circ}\text{C/W}$
Typical Thermal Resistance ^{NOTE3}		$R_{\theta JA}$	50							$^{\circ}\text{C/W}$
Operating Junction Temperature Range		T_J	-55 ~ +175							$^{\circ}\text{C}$
Storage Temperature Range		T_{STG}	-55 ~ +175							$^{\circ}\text{C}$

NOTE1: Measured at 1MHz and applied average voltage of 4V D.C.

NOTE2: Thermal resistance junction to lead, 6.0mm 2 copper pads to each terminal.

NOTE3: Thermal resistance junction to ambient, 6.0m 2 copper pads to each terminal.



TYPICAL CHARACTERISTICS

Figure. 1 Typical Forward Current Derating Curve

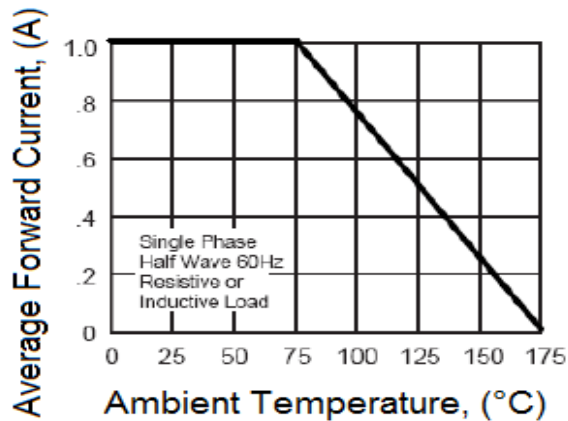


Figure. 2 Maximum Non-Repetitive Forward Surge Current

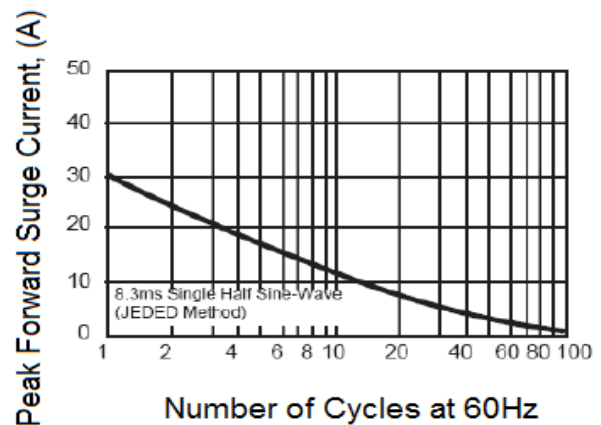


Figure. 3 Typical Instantaneous Forward Characteristics

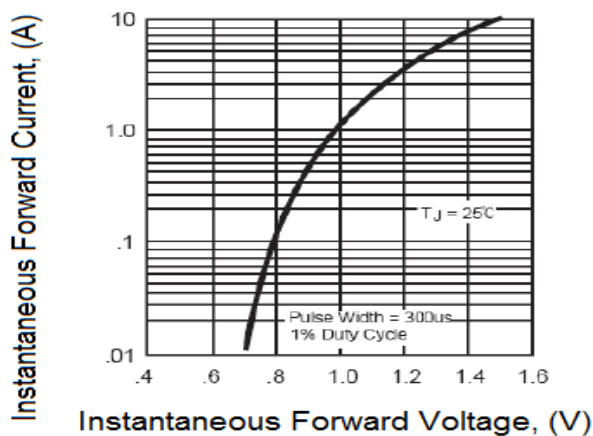


Figure. 4 Typical Reverse Characteristics

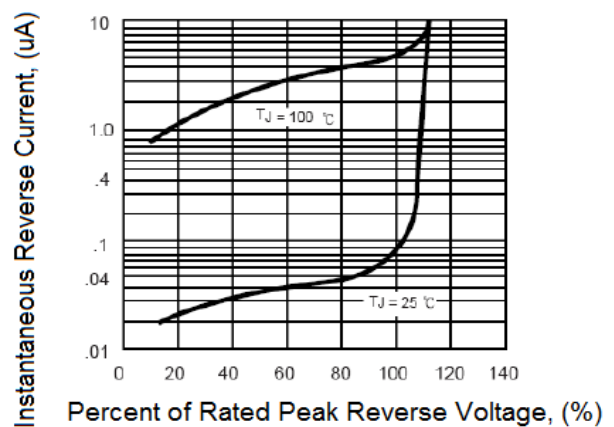
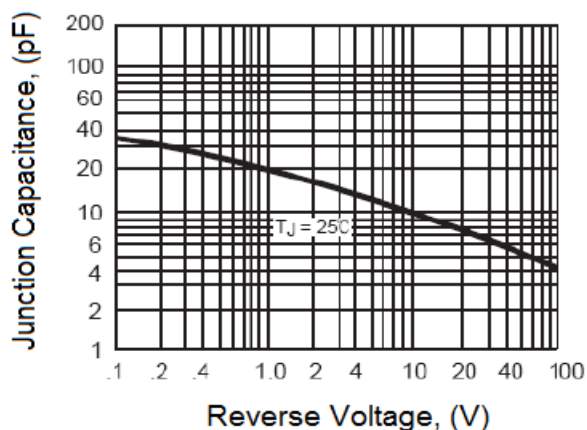


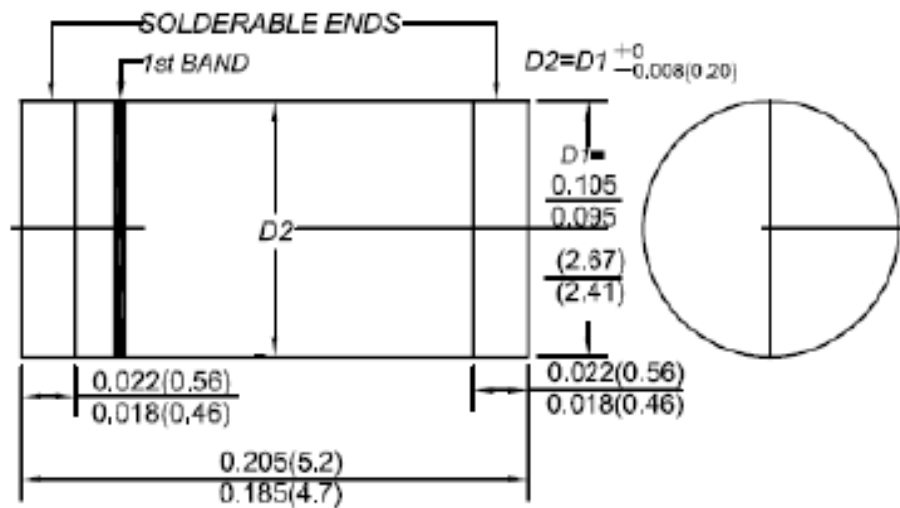
Figure. 5 Typical Junction Capacitance





PACKAGE INFORMATION

Dimension in DO-123AB (Unit: mm)





IMPORTANT NOTICE

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